Listing of Claims in the Application

This Listing of Claims replaces, without prejudice, all previous versions and listing of claims in this Application.

1. (Currently amended) A master plate for fabricating a stamper plate for production of an optical storage medium with information such as a CD or a DVD, the master plate comprising a substrate, an adhesive layer, and a single photoresist layer provided thereon, while parts of the photoresist layer exposed to light of a predetermined frequency are soluble in a solvent for creating a hole pattern with recesses in the photoresist layer, characterized in that the solubility exhibits a gradient along the normal to the photoresist layer by diffusion of molecules of the adhesive into the photoresist layer, wherein the adhesive layer turns into a first subphotoresist layer through a crosslinking reaction of the photoresist layer with the adhesive layer, the photoresist layer forming a second subphotoresist layer, the solubility on the side near the substrate being less soluble than the solubility on the opposite, upper side of the photoresist layer so that bottoms of the recesses obtain a flowing contour.

2. (Canceled)

3. (Previously presented) A master plate according to claim 1, characterized in that parts of the photoresist layer exposed to laser light having a wavelength of 200-500 nm are soluble in the solvent.

4. (Previously presented) A master plate according to claim 3, characterized in that the solvent is an alkaline solvent.

5. (Currently amended) A method for fabricating a master plate for fabricating a stamper plate, wherein on a substrate an adhesive layer and a single photoresist layer is provided, wherein parts of the photoresist layer exposed to light of a predetermined frequency are soluble in a solvent for creating a hole pattern with recesses in the photoresist layer, characterized in that the solubility exhibits a gradient along the normal to the

photoresist layer by diffusion of molecules of the adhesive into the photoresist layer, wherein the adhesive layer turns into a first subphotoresist layer through a crosslinking reaction of the photoresist layer with the adhesive layer, the photoresist layer forming a second subphotoresist layer, the solubility on the side near the substrate being less than the solubility on the opposite, upper side of the photoresist layer

6. (Canceled)

7. (Currently amended) A method according to claim 5 characterized in that the method further comprises the following steps:

providing directly on the substrate an adhesive such as n-(2-amino-ethyl)-3-aminopropyl-trimethoxysilane, hexamethyldisilazane (HMDS) and/or trimethylsilyldiethylamine (TMSDEA);

providing the photoresist layer on the adhesive applied;

~~allowing formation, through a crosslinking reaction between the adhesive and the photoresist layer provided directly thereon~~.

8. (Original) A method according to claim 7, characterized in that the adhesive, directly upon application, is rinsed with a rinsing agent such as water for a relatively short period of time.

9. (Original) A method according to claim 8, characterized in that the relatively short rinsing period with water takes 5 seconds at a maximum.

10. (Canceled)

11. (Canceled)

12. (Previously presented) A method according to claim 5, characterized in that subphotoresist layers are exposed according to a predetermined pattern, after which the thus exposed parts are dissolved in the solvent and are rinsed off, and after which the surface of

the photoresist layer of the master plate is provided with a relatively thin metal layer.

13. (Previously presented) A method according to claim 5, characterized in that the method further comprises the step of fabricating a stamper plate by a galvanic process as a negative copy of the master plate.

14. (Original) A method according to claim 13, characterized in that the method further comprises the step of fabricating an optical storage medium by an injection molding process with the stamper plate.

15 (Canceled)

16. (Canceled)

17. (New) A master plate according to claim 1 wherein the adhesive layer has a thickness of from 30 to 40 nm.

18. (New) The method according to claim 5 wherein the adhesive layer has a thickness of from 30 to 40 nm.